

HIGH VOLTAGE POWER SCHOTTKY RECTIFIER

MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	2 A
V_{RRM}	100 V
$T_j(\text{max})$	175°C
$V_F(\text{max})$	0.70 V

FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- HIGH JUNCTION TEMPERATURE CAPABILITY
- GOOD TRADE OFF BETWEEN LEAKAGE CURRENT AND FORWARD VOLTAGE DROP
- LOW LEAKAGE CURRENT
- AVALANCHE CAPABILITY SPECIFIED



DESCRIPTION

Axial Power Schottky rectifier suited for Switch Mode Power Supply and high frequency DC/DC converters. Packaged in DO-41, this device is intended for use in low voltage, high frequency inverters and small battery chargers.

ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	100	V
$I_{F(RMS)}$	RMS forward current	10	A
$I_{F(AV)}$	Average forward current	2	A
I_{FSM}	Surge non repetitive forward current	50	A
I_{RRM}	Repetitive peak reverse current	1	A
P_{ARM}	Repetitive peak avalanche power	1500	W
T_{stg}	Storage temperature range	- 65 to + 175	°C
T_j	Maximum operating junction temperature *	175	°C
dV/dt	Critical rate of rise of reverse voltage	10000	V/μs

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j - a)}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-a)}$	Junction to ambient	Lead length = 10 mm	100	$^{\circ}\text{C/W}$
$R_{th(j-l)}$	Junction to lead	Lead lenght = 10 mm	35	

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I_R *	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			1	μA
		$T_j = 125^{\circ}\text{C}$			0.2	0.5	mA
V_F **	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 2 \text{ A}$			0.86	V
		$T_j = 125^{\circ}\text{C}$	$I_F = 2 \text{ A}$		0.65	0.70	
		$T_j = 25^{\circ}\text{C}$	$I_F = 4 \text{ A}$			0.92	
		$T_j = 125^{\circ}\text{C}$	$I_F = 4 \text{ A}$		0.72	0.78	

Pulse test : * $t_p = 5 \text{ ms}, \delta < 2\%$

** $t_p = 380 \mu\text{s}, \delta < 2\%$

To evaluate the maximum conduction losses use the following equation :
 $P = 0.62 \times I_{F(AV)} + 0.04 \times I_{F}^2(\text{RMS})$

Fig. 1: Conduction losses versus average current.

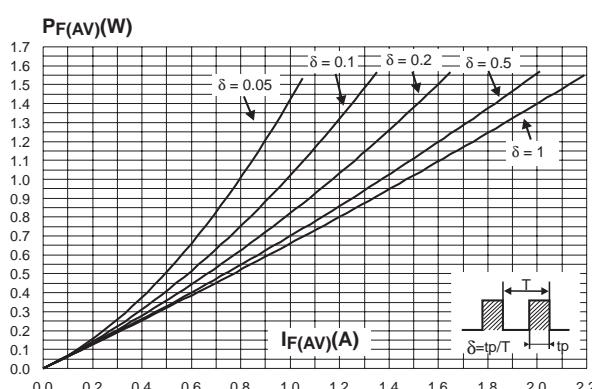


Fig. 3: Normalized avalanche power derating versus pulse duration.

Fig. 2: Average forward current versus ambient temperature ($\delta=0.5$).

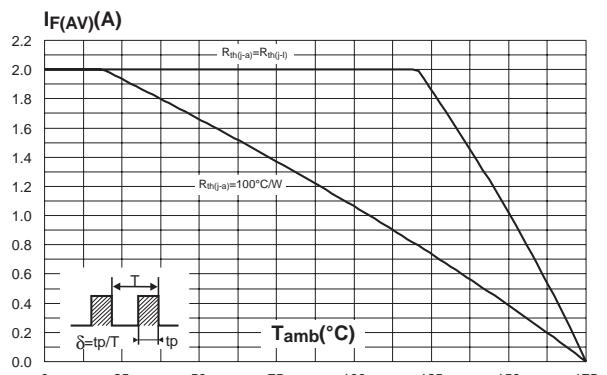


Fig. 4: Normalized avalanche power derating versus junction temperature.

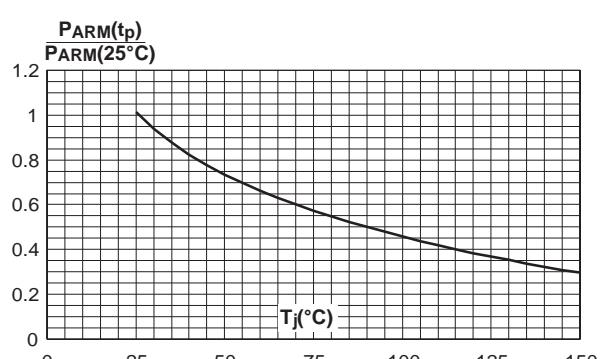
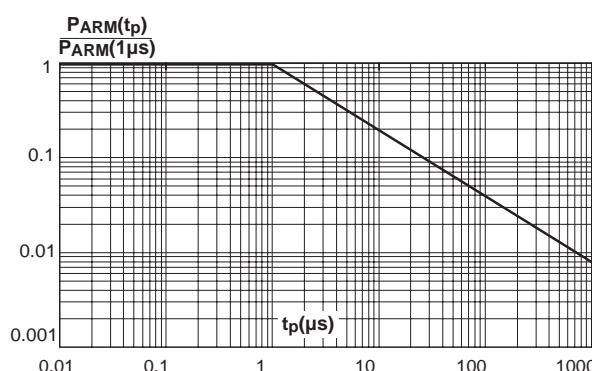


Fig. 5: Non repetitive surge peak forward current versus overload duration (maximum values).

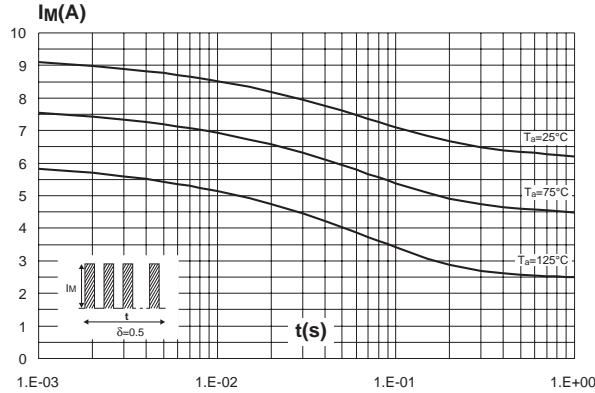


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values).

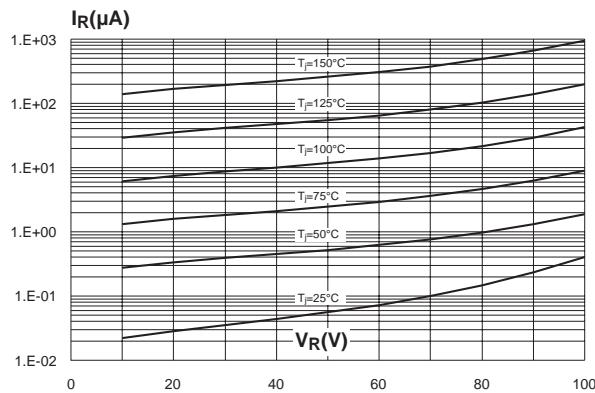


Fig. 9-1: Forward voltage drop versus forward current (low level).

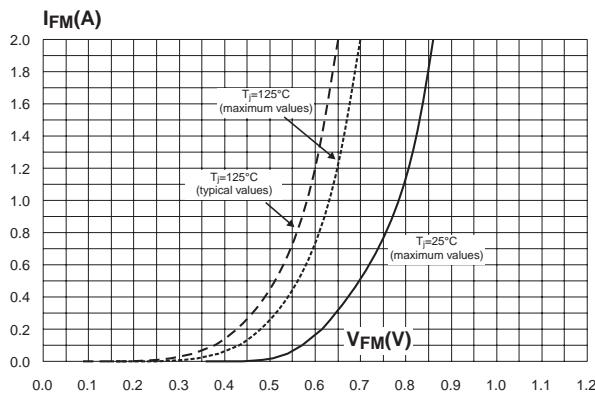


Fig. 6: Relative variation of thermal impedance junction to ambient versus pulse duration.

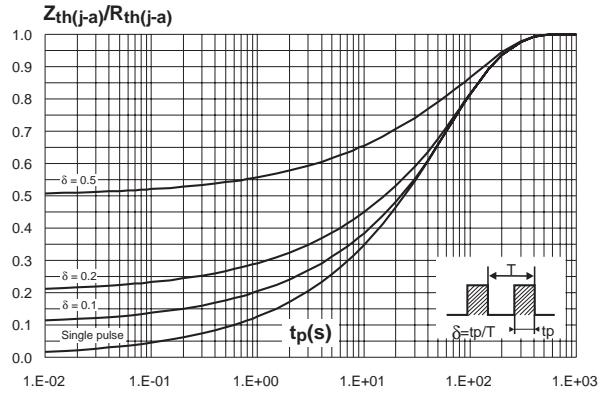


Fig. 8: Junction capacitance versus reverse voltage applied (typical values).

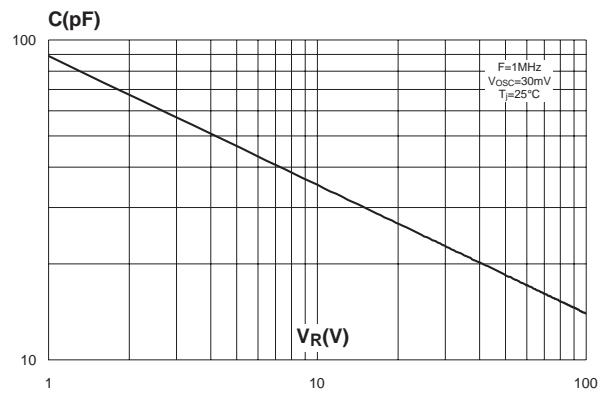
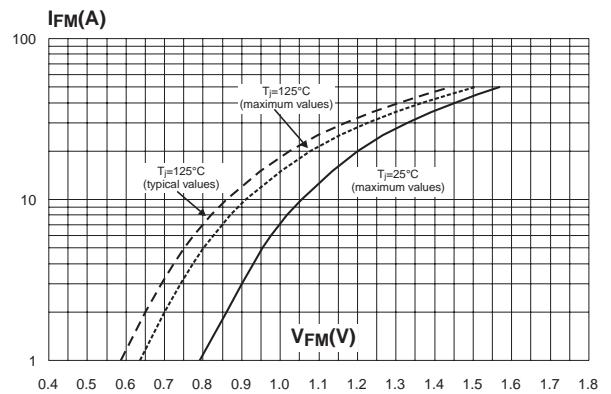
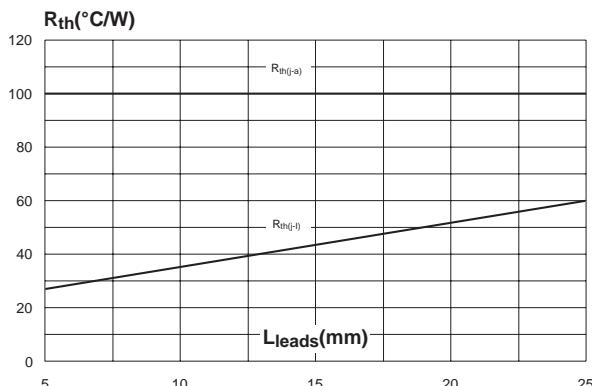


Fig. 9-2: Forward voltage drop versus forward current (high level).



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Fig. 10: Thermal resistance versus lead length.



PACKAGE MECHANICAL DATA

DO-41 (plastic)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.07	5.20	0.160	0.205
B	2.04	2.71	0.080	0.107
C	28		1.102	
D	0.712	0.863	0.028	0.034

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS2H100	STPS2H100 cathode ring	DO-41	0.34 g	2000	Ammopack
STPS2H100RL	STPS2H100 cathode ring			5000	Tape & Reel

- EPOXY MEETS UL94,V0

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